

ENGINEERING DEPT.	PRODUCT SPECIFICATION	SPEC.NO.: SPCP072A
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1. SCOPE:

This specification contains the test requirement

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering part design standards

3. APPLICABLE SERIES NO.: CPLB Series

(P/N: CPLB0VA100*-NH)

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 P.C. Board Layout: See attached drawings



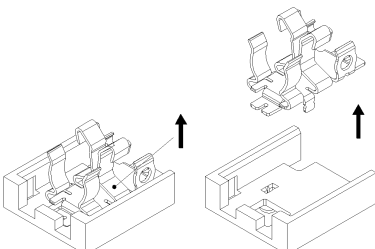
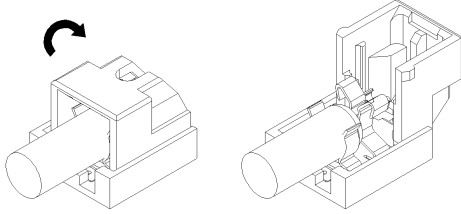
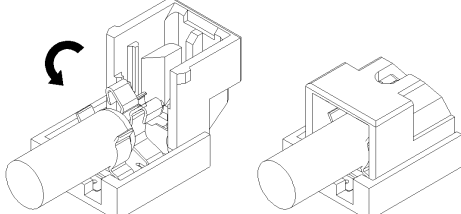
REVIEWED : David APPROVED : Eisley VERIFIED : Clark .

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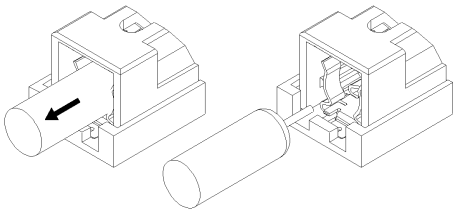
7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.0A max. 3000V AC/DC max.
7.2	Contact resistance	Dry circuit of DC 20mV max. , 10mA max.	Less than 20 mΩ
7.3	Dielectric strength	Applied AC 3000V 1minute	No change
7.4	Insulation resistance	Applied DC 500 V	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push Pin for insulator base at speed 25 ± 3 mm per minute 	More than 500 gf
8.2	Open Cover force	Speed 25 ± 3 mm per minute (With $\phi 4.30$ mm CCFL) 	More than 300 gf
8.3	Close Cover force	Speed 25 ± 3 mm per minute (With $\phi 4.30$ mm CCFL) 	Less than 2000 gf

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8.4	CCFL retention force	Speed 25 ± 3 mm per minute (With $\phi 0.60$ mm Filament) 	More than 500 gf
8.5	Durability	CCFL shall be subjected to 10 cycles of insertion and withdrawal	Open Cover force: More than 200 gf Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	$85 \pm 2^\circ\text{C}$, 250 hours	No damage
9.4	Humidity	$40 \pm 2^\circ\text{C}$, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3 Insulation resistance: More than 1000 MΩ
9.5	Temperature cycling	One cycle consists of : (1) $-55^{+0}_{-3}^\circ\text{C}$, 30 min. (2) Room temp. 10-15 min. (3) $85^{+3}_{-0}^\circ\text{C}$, 30 min. (4) Room temp. 10-15 min. Total cycles : 5 cycles	Appearance: No damage Contact resistance: Less than twice of initial



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9.6	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Solder ability	Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: $245 \pm 5^{\circ}\text{C}$	Minimum: 90% of immersed area
9.8	Resistance to soldering heat	Lead-Free Process for SMT Type: Refer Reflow temperature profile(11.1)	No damage

10. AMBIENT TEMPERATURE RANGE: -25 to $+85^{\circ}\text{C}$

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Paste

